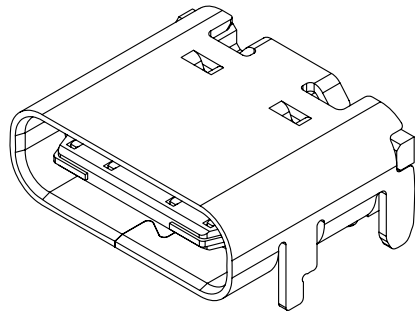
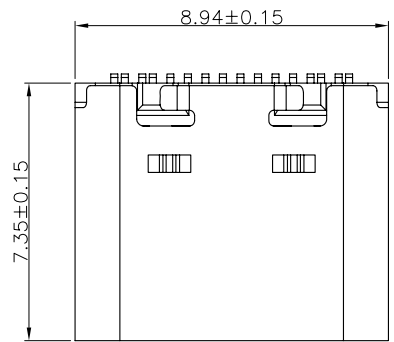


REV	ECN NO.	DISCRIPTION	CHEKED/DATE	APPD/DATE

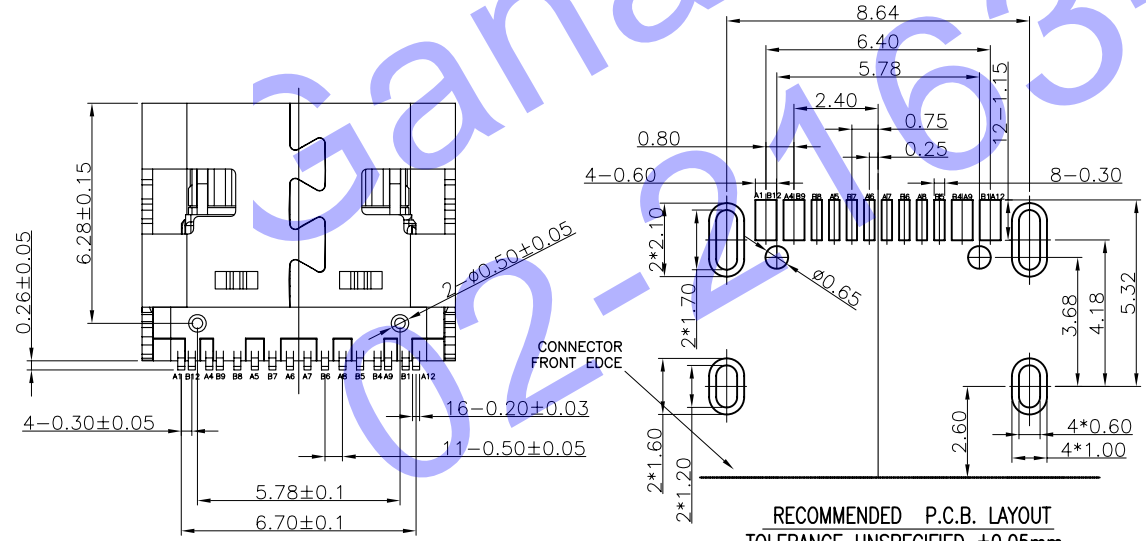
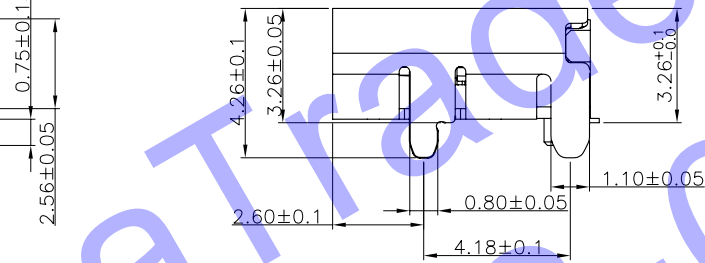
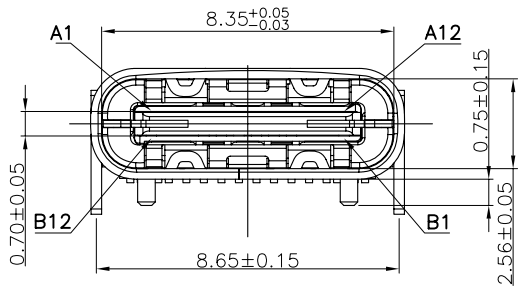


NOTES: 1.MATERIAL:
MOLDING: LCP UL94 V-0
CONTACT:COPPER ALLOY.
GOLD PLATED Min ON CONTACT AREA,100u"
Min TIN (LEAD FREE) ON SOLDER AREA,
SHELL: SUS304-H,T=0.30±0.03mm
50u" NICKEL PLATING OVER ALL.
SHILD:SUS304-H,T=0.12±0.03mm

2.MECHANICAL:
INSERTION: 5~20N.
EXTRACTION: 8~20N AFTER TEST.
DURABILITY: 10000 CYCLES

3.ELECTRICAL:
CURRENT: 5A FOR VBUS;
1.25A FOR GND PIN.
0.25A FOR OTHER.
VOLTAGE: 20 V MAX
WITHSTANDING VOLTAGE: 100V AC R.M.S.
CONTACT RESISTANCE: 40mΩ MAX.
INSULATION RESISTANCE: 100MΩ MIN.

4.ENVIRONMENTAL
TEMPERATURE RANGE -25°C ~ +85°C



A1	GND	B12	GND
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	DP1	B7	DN2
A7	DN1	B6	DP2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A12	GND	B1	GND
PIN	SIGNAL NAME	PIN	SIGNAL NAME

H D C 有限公司

.X: ±0.25	.X: ±1°	APP.	DWG NO.	UC-020-02
.XX: ±0.15	.X: ±0.5°	CHK.	TITLE	USB 3.1 C 16PF SMT 板上母座 单排短体2.0版
.XXX: ±0.05	.XX: ±0.02°	DGN.	15.11.06	SERIES
UNIT: mm		DRW.	15.11.06	
SCALE: 1:1		SHEET: 1/1		